

# MOS FIELD EFFECT TRANSISTOR 2SK3325B

# **SWITCHING N-CHANNEL POWER MOSFET**

#### **DESCRIPTION**

The 2SK3325B is N-channel MOSFET device that features a low gate charge and excellent switching characteristics, and designed for high voltage applications such as switching power supply, AC adapter.

### **FEATURES**

Low gate charge

 $Q_G = 20 \text{ nC TYP.}$  (ID = 10 A,  $V_{DD} = 400 \text{ V}$ ,  $V_{GS} = 10 \text{ V}$ )

- Gate voltage rating: ±30 V
- Low on-state resistance

 $R_{DS(on)} = 0.85 \Omega MAX. (Vgs = 10 V, ID = 5.0 A)$ 

Avalanche capability ratings

#### ORDERING INFORMATION

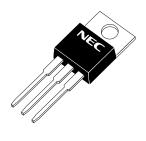
PART NUMBER	LEAD PLATING	PACKING	PACKAGE
2SK3325B-S19-AY Note	Pure Sn (Tin)	Tube 50 p/tube	TO-220AB (MP-25) typ. 1.9 g
2SK3325B-ZK-E1-AY Note	Pure Sn (Tin)	Tape 800 p/reel	TO-263 (MP-25ZK) typ. 1.48 g
2SK3325B-ZK-E2-AY Note	Pure Sn (Tin)	Tape 800 p/reel	TO-263 (MP-25ZK) typ. 1.48 g

**Note** Pb-free (This product dose not contain Pb in external electrode.)

(TO-220AB)

# ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

	. 4		
Drain to Source Voltage (Vcs = 0 V)	VDSS	500	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±30	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±10	Α
Drain Current (pulse) Note1	ID(pulse)	±40	Α
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T1</sub>	1.5	W
Total Power Dissipation (Tc = 25°C)	P <sub>T2</sub>	85	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Single Avalanche Current Note2	las	10	Α
Single Avalanche Energy Note2	Eas	10.7	mJ



(TO-263)



**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

2. Starting Tch = 25°C, VdD = 150 V, Rg = 25  $\Omega$  , Vgs = 20  $\rightarrow$  0 V

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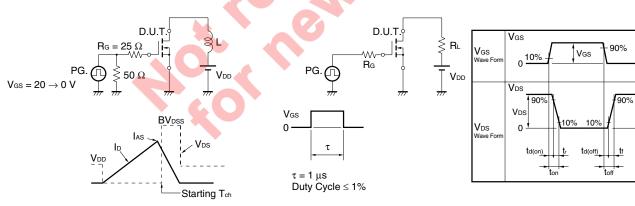
**ELECTRICAL CHARACTERISTICS (TA = 25°C)** 

CHRACTERISTICS	SYMBOL	TEST CONDITIONS		TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V			100	μA
Gate Leakage Current	Igss	Vgs = ±30 V, Vps = 0 V			±100	nA
Gate Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.5		3.5	V
Forward Transfer Admittance Note	y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 5.0 A	2.0	3.9		S
Drain to Source On-state Resistance Note	R <sub>DS(on)</sub>	Vgs = 10 V, ID = 5.0 A		0.76	0.85	Ω
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V		1270		pF
Output Capacitance	Coss	V <sub>G</sub> S = 0 V		210		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		6		pF
Turn-on Delay Time	td(on)	V <sub>DD</sub> = 150 V, I <sub>D</sub> = 5.0 A		19		ns
Rise Time	tr	Vgs = 10 V		6.5		ns
Turn-off Delay Time	td(off)	$R_G = 10 \Omega$		31		ns
Fall Time	tf	RL = 60 Ω		5		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 400 V		20		nC
Gate to Source Charge	Qgs	Vgs = 10 V		9.5		nC
Gate to Drain Charge	<b>Q</b> GD	I <sub>D</sub> = 10 A		5.5		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	IF = 10 A, VGS = 0 V		0.98	1.5	V
Reverse Recovery Time	trr	IF = 10 A, VGS = 0 V		440		ns
Reverse Recovery Charge	Qrr	di/dt = 50 A/μs		2000		nC

Note Pulsed

## TEST CIRCUIT 1 AVALANCHE CAPABILITY

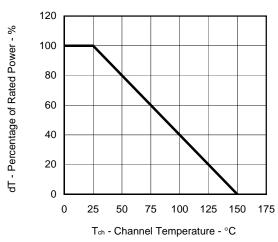
# TEST CIRCUIT 2 SWITCHING TIME



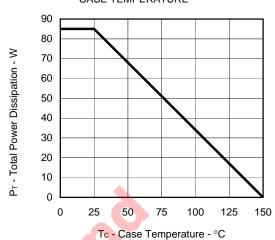
# **TEST CIRCUIT 3 GATE CHARGE**

# TYPICAL CHARACTERISTICS (TA = 25°C)

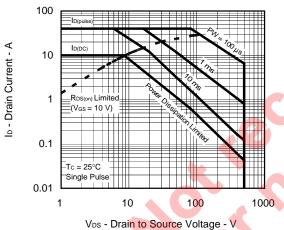
#### DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



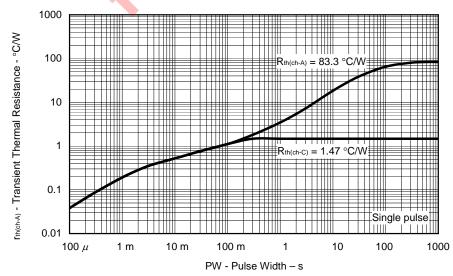
#### TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



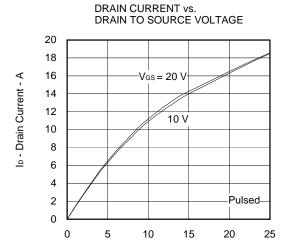
#### FORWARD BIAS SAFE OPERATING AREA



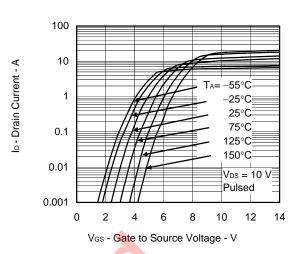




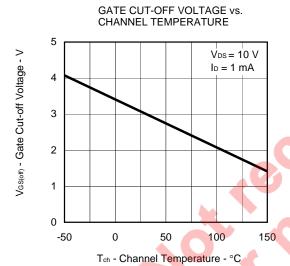
3

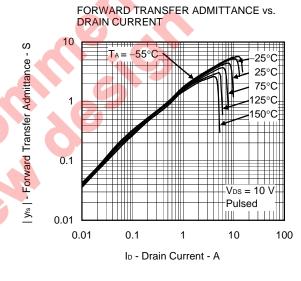


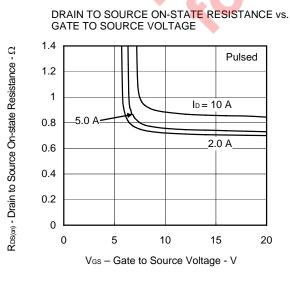
V<sub>DS</sub> - Drain to Source Voltage - V

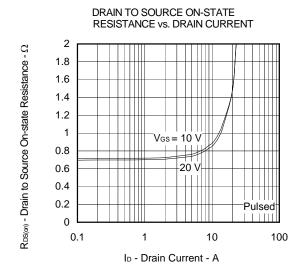


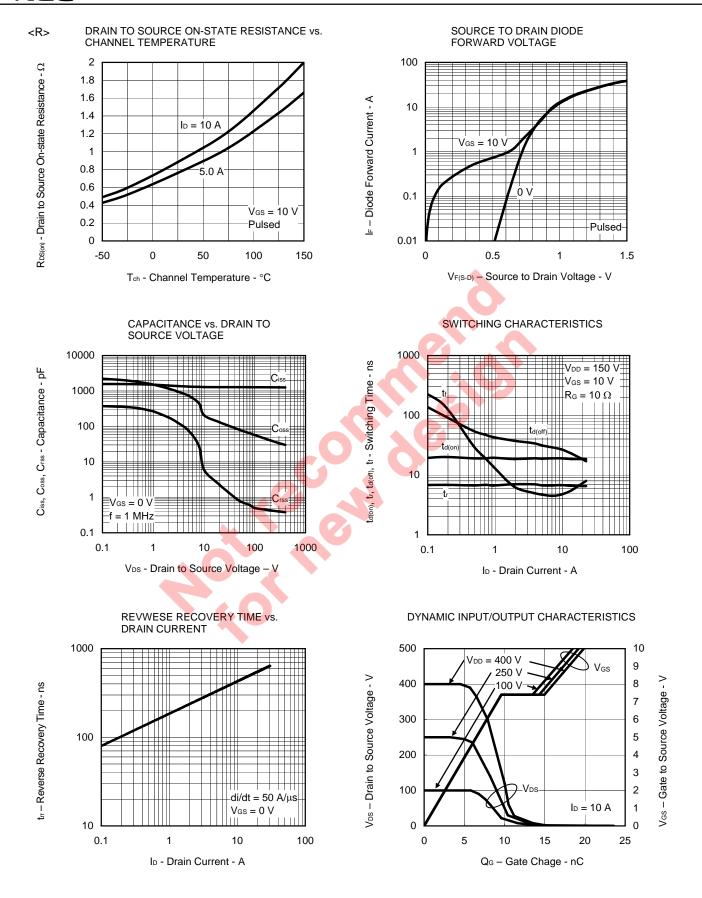
FORWARD TRANSFER CHARACTERISTICS



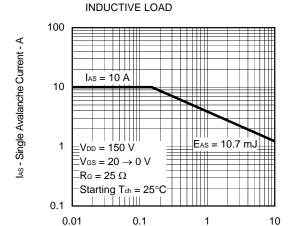






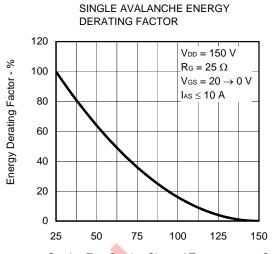


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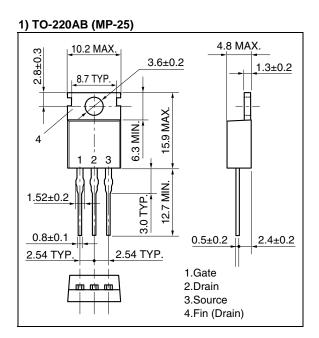


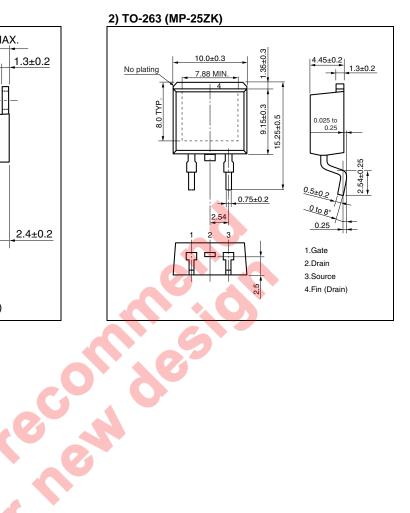
L - Inductive Load - H

SINGLE AVALANCHE CURRENT vs.

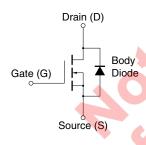


# **PACKAGE DRAWINGS (Unit: mm)**





#### **EQUIVALENT CIRCUIT**



**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

NEC 2SK3325B

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